Matthias Hunstig

List of Publications by Year
in descending order

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27	475	1040056 9	1058476 14
papers	citations	h-index	g-index

28	28	28	384
all docs	docs citations	times ranked	citing authors

#	Article	IF	Citations
1	Using complex multi-dimensional vibration trajectories in ultrasonic bonding and welding. Sensors and Actuators A: Physical, 2019, 295, 653-662.	4.1	12
2	Modellbildung fÃ¼r das Ultraschall-Drahtbonden. Intelligente Technische Systeme, Lolˆsungen Aus Dem Spitzencluster Itâ€™s OWL, 2019, , 17-44.	0.4	0
3	Grundlagen des Ultraschall-Drahtbondens. Intelligente Technische Systeme, Lolˆsungen Aus Dem Spitzencluster Itâ€™s OWL, 2019, , 5-15.	0.4	0
4	Mehrzieloptimierung und Verhaltensanpassung am Bondautomaten. Intelligente Technische Systeme, Lolˆsungen Aus Dem Spitzencluster Itâ€™s OWL, 2019, , 53-64.	0.4	0
5	Simulation und Validierung des Bondprozesses. Intelligente Technische Systeme, Lolˆsungen Aus Dem Spitzencluster Itâ€™s OWL, 2019, , 45-51.	0.4	0
6	Numerical and statistical investigation of weld formation in a novel two-dimensional copper-copper bonding process. , 2018, , .		5
7	Experimental investigations on the impact of bond process parameters in two-dimensional ultrasonic copper bonding. , 2018, , .		4
8	Intelligent Production of Wire Bonds using Multi-Objective Optimization â€“ Insights, Opportunities and Challenges. International Symposium on Microelectronics, 2018, 2018, 000572-000577.	0.0	1
9	Piezoelectric Inertia Motorsâ€”A Critical Review of History, Concepts, Design, Applications, and Perspectives. Actuators, 2017, 6, 7.	2.3	98
10	Multi-dimensional Ultrasonic Copper Bonding â€“ New Challenges for Tool Design. International Symposium on Microelectronics, 2017, 2017, 000438-000443.	0.0	0
11	Validated simulation of the ultrasonic wire bonding process. , 2016, , .		3
12	Micro wear modeling in copper wire wedge bonding. , 2016, , .		3
13	Reliable Manufacturing of Heavy Copper Wire Bonds Using Online Parameter Adaptation. , 2016, , .		6
14	High-velocity operation of piezoelectric inertia motors: experimental validation. Archive of Applied Mechanics, 2016, 86, 1733-1741.	2.2	14
15	Modeling of the stick-slip effect in heavy copper wire bonding to determine and reduce tool wear. , 2015, , .		12
16	Modeling and simulation of the ultrasonic wire bonding process. , 2015, , .		7
17	Experimental and Numerical Simulation Study of Pre-deformed Heavy Copper Wire Wedge Bonds. International Symposium on Microelectronics, 2014, 2014, 000289-000294.	0.0	9
18	Enhanced energy harvesting using multiple piezoelectric elements: Theory and experiments. Sensors and Actuators A: Physical, 2013, 200, 138-146.	4.1	50

#	Article	IF	Citations
19	Stickâ€“slip and slipâ€“slip operation of piezoelectric inertia drives. Part I: Ideal excitation. Sensors and Actuators A: Physical, 2013, 200, 90-100.	4.1	78
20	Stick-slip and slip-slip operation of piezoelectric inertia drivesâ€”Part II: Frequency-limited excitation. Sensors and Actuators A: Physical, 2013, 200, 79-89.	4.1	27
21	Modelling the friction contact in an inertia motor. Journal of Intelligent Material Systems and Structures, 2013, 24, 1380-1391.	2.5	21
22	Increasing the power of piezoelectric energy harvesters by magnetic stiffening. Journal of Intelligent Material Systems and Structures, 2013, 24, 1332-1342.	2.5	9
23	An efficient simulation technique for high-frequency piezoelectric inertia motors. , 2012, , .		0
24	Analytical determination of characteristic frequencies and equivalent circuit parameters of a piezoelectric bimorph. Journal of Intelligent Material Systems and Structures, 2012, 23, 15-23.	2.5	20
25	Frequency tuning of piezoelectric energy harvesters by magnetic force. Smart Materials and Structures, 2012, 21, 035019.	3.5	84
26	Drive Signals for Maximizing the Velocity of Piezoelectric Inertia Motors. Journal of the Korean Physical Society, 2010, 57, 938-941.	0.7	9
27	Parameter Identification and Model Validation for the Piezoelectric Actuator in an Inertia Motor. Journal of the Korean Physical Society, 2010, 57, 952-954.	0.7	3